优尚

YOUSHANG SEMICONDUCTOR

设计研发新型功率器件

各类小信号开关

中低压及高压大电流等场效应管

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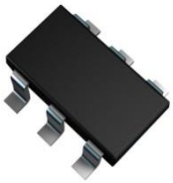
Features & Benefits

- BV_{CEO} > 80V
- I_{CM} = 1A Peak Pulse Current
- General purpose NPN transistors ideally suited for low power amplification and switching applications
- Dual transistors in a single SOT26 package taking half the footprint of two equivalent transistors in SOT23
- Epitaxial Planar Die Construction

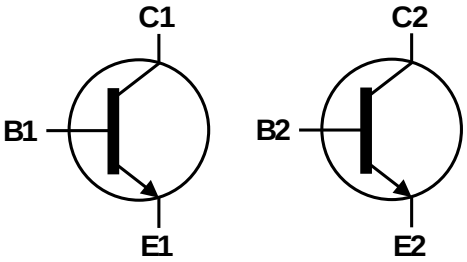
Mechanical Data

- Case: SOT26
- Case Material: Molded Plastic, “Green” Molding Compound; UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish Annealed over Copper Leadframe; Solderable per MIL-STD-202, Method 208 e3
- Weight: 0.015 grams (Approximate)

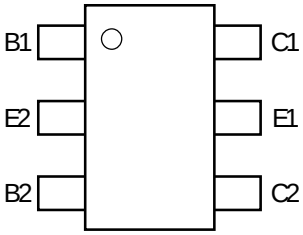
SOT26



Top View



Device Symbol



Top View
Pin-Out

Absolute Maximum Ratings (@T_A = +25°C unless otherwise specified)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V_{CBO}	100	V
Collector-Emitter Voltage	V_{CEO}	80	V
Emitter-Base Voltage	V_{EBO}	6	V
Continuous Collector Current	I_C	500	mA
Peak Pulse Collector Current	I_{CM}	1	A

Thermal Characteristics @T_A = 25°C unless otherwise specified

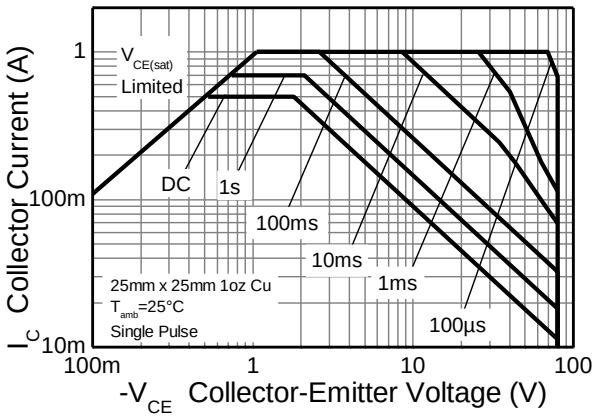
Characteristic		Symbol	Value	Unit
Power Dissipation Linear Derating Factor	(Notes 6 & 7)	P_D	1.28 10.3	W mW/°C
	(Notes 5 & 7)		0.90 7.14	
Thermal Resistance, Junction to Ambient	(Notes 6 & 7)	$R_{\theta JA}$	97	°C/W
	(Notes 5 & 7)		140	
Thermal Resistance, Junction to Lead	(Note 8)	$R_{\theta JL}$	103	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

ESD Ratings (Note 9)

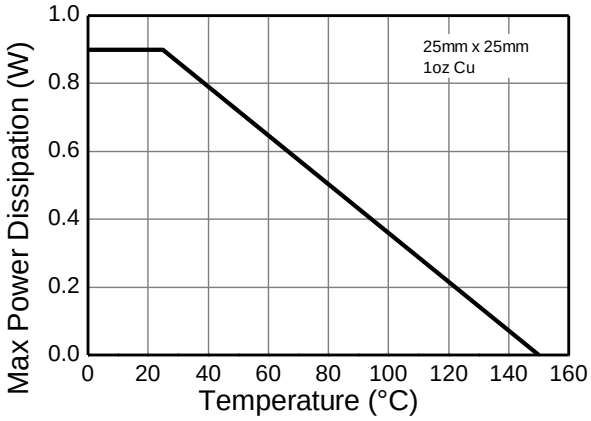
Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

Notes:
5. For a device surface mounted on 25mm x 25mm x 1.6mm FR4 PCB with high coverage of single sided 1oz copper, in still air conditions; the device is measured when operating in a steady-state condition.
6. Same as Note 5, except the device is measured at t ≤ 5 seconds.
7. For a dual device with one active die.
8. Thermal resistance from junction to solder-point (at the end of the collector lead).
9. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

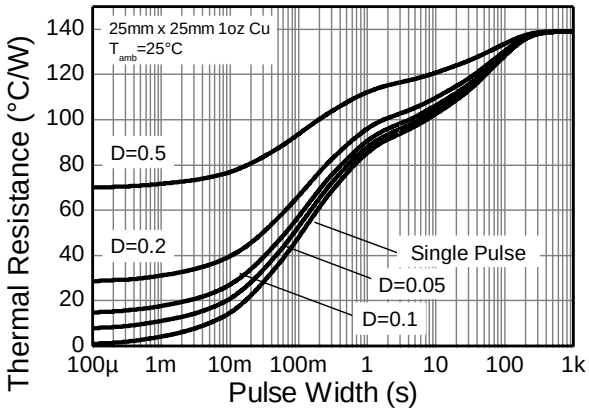
Thermal Characteristics and Derating Information



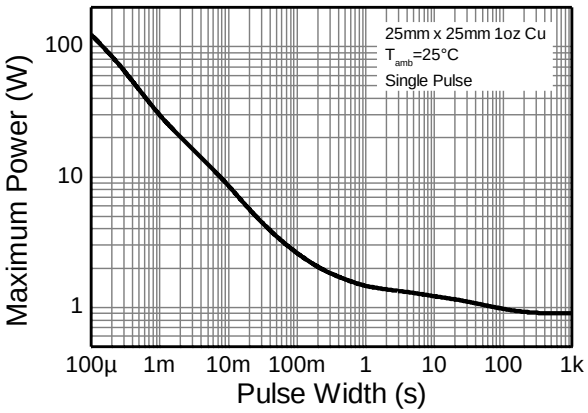
Safe Operating Area



Derating Curve



Transient Thermal Impedance



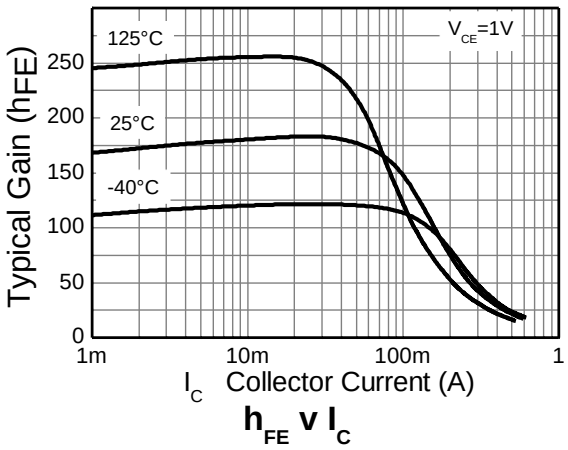
Pulse Power Dissipation

Electrical Characteristics (@T_A = +25°C unless otherwise specified.)

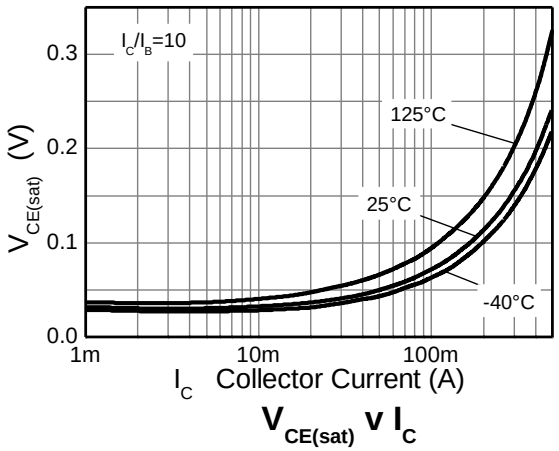
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS						
Collector-Base Breakdown Voltage	BV_{CBO}	100	—	—	V	I_C = 100μA, I_E = 0
Collector-Emitter Breakdown Voltage (Note 10)	BV_{CEO}	80	—	—	V	I_C = 1mA, I_B = 0
Emitter-Base Breakdown Voltage	BV_{EBO}	6	—	—	V	I_E = 100μA, I_C = 0
Collector-Base Cut-Off Current	I_{CBO}	—	—	100	nA	V_{CB} = 80V, I_E = 0
Collector-Emitter Cut-Off Current	I_{CES}	—	—	100	nA	V_{CE} = 80V, I_B = 0
Emitter-base Cut-Off Current	I_{EBO}	—	—	100	nA	V_{EB} = 5V, I_C = 0
ON CHARACTERISTICS (Note 10)						
DC Current Gain	h_{FE}	100	—	—	—	I_C = 10mA, V_{CE} = 1V
		100	—	—		I_C = 100mA, V_{CE} = 1V
Collector-Emitter Saturation Voltage	$V_{CE(sat)}$	—	—	0.25	V	I_C = 100mA, I_B = 10mA
Base-Emitter Turn-On Voltage	$V_{BE(on)}$	—	—	1.20	V	I_C = 100mA, V_{CE} = 1V
SMALL SIGNAL CHARACTERISTICS						
Current Gain-Bandwidth Product	f_T	100	163	—	MHz	V_{CE} = 2V, I_C = 10mA, f = 100MHz
Output Capacitance	C_{obo}	—	7	—	pF	V_{CB} = 10V, f = 1MHz

Note: 10. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%.

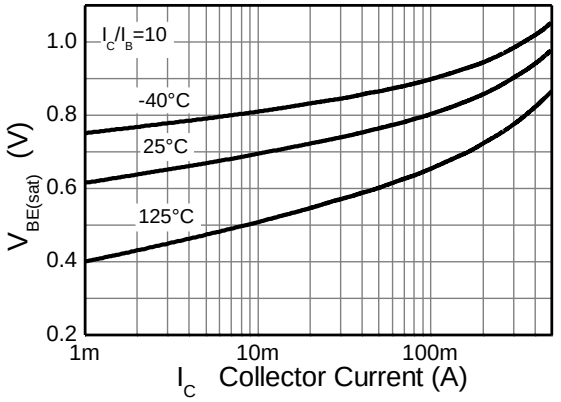
Typical Electrical Characteristics (@T_A = +25°C unless otherwise specified.)



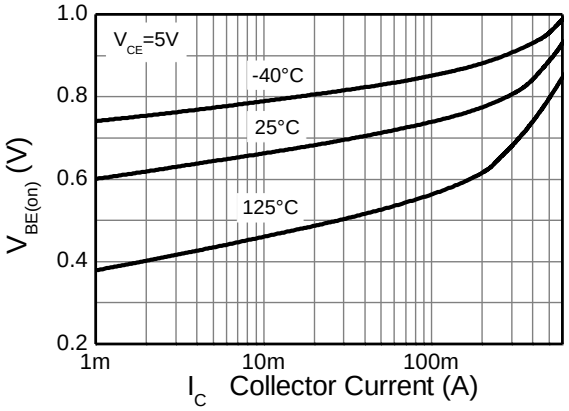
h_{FE} v I_C



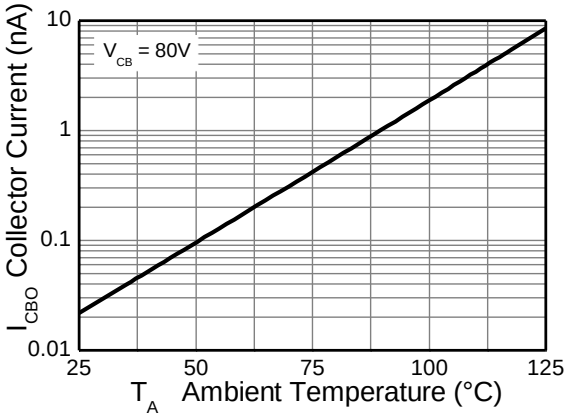
$V_{CE(sat)}$ v I_C



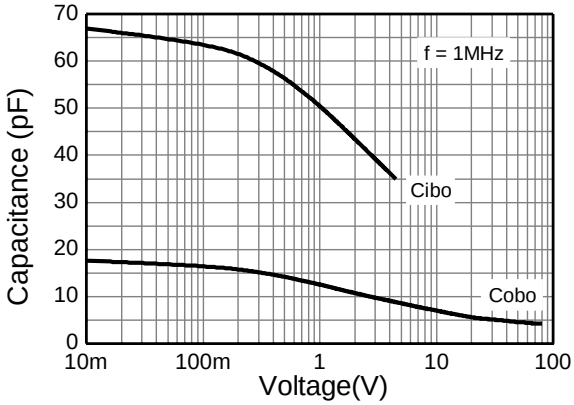
$V_{BE(sat)}$ v I_C



$V_{BE(on)}$ v I_C

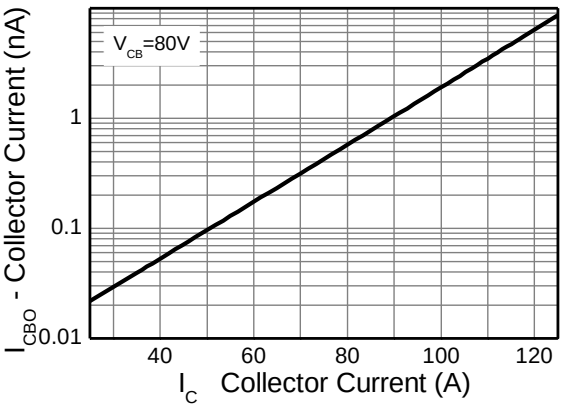


I_{CBO} v T_A

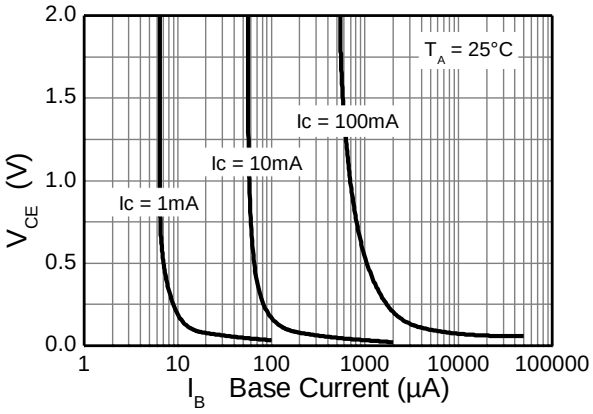


Capacitance v Voltage

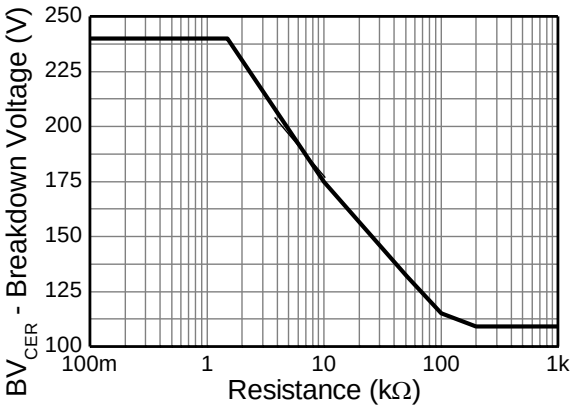
Typical Electrical Characteristics – Continued (@T_A = +25°C unless otherwise specified.)



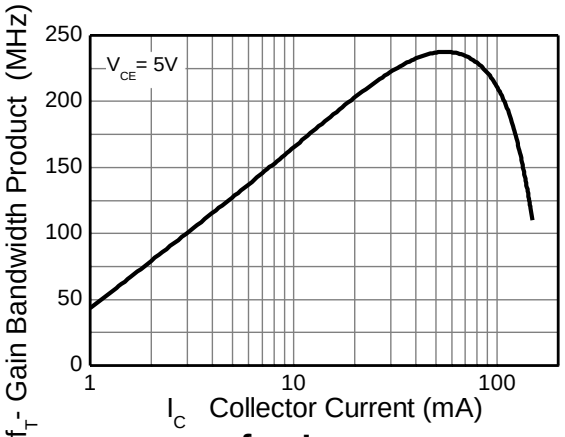
Collector-Cutoff Current vs T_A



V_{CE} v I_B

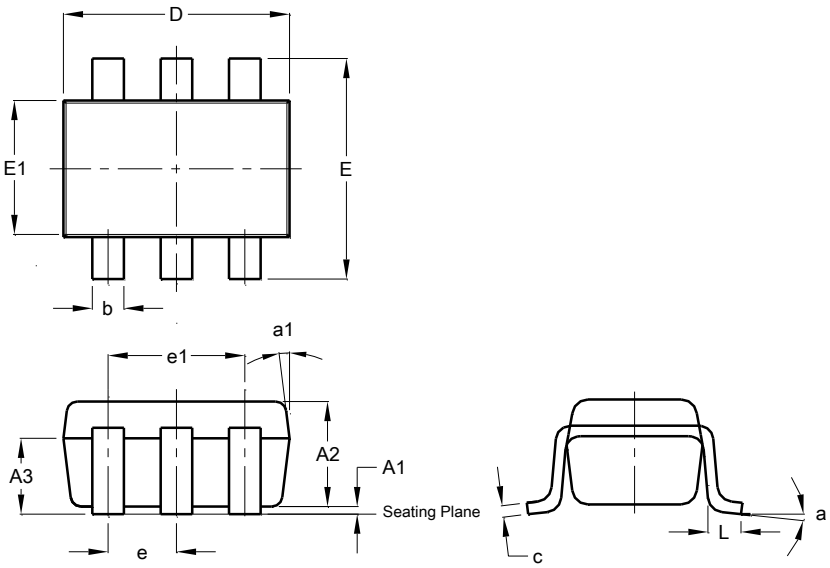


BV_{CER} v R



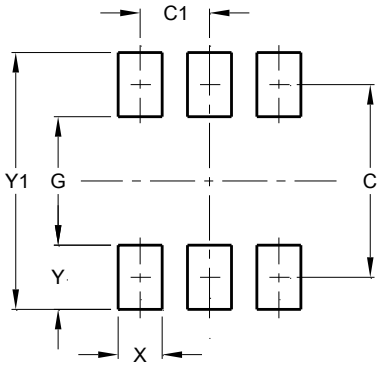
f_T v I_C

Package Outline



SOT26			
Dim	Min	Max	Typ
A1	0.013	0.10	0.05
A2	1.00	1.30	1.10
A3	0.70	0.80	0.75
b	0.35	0.50	0.38
c	0.10	0.20	0.15
D	2.90	3.10	3.00
e	-	-	0.95
e1	-	-	1.90
E	2.70	3.00	2.80
E1	1.50	1.70	1.60
L	0.35	0.55	0.40
a	-	-	8°
a1	-	-	7°
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
C	2.40
C1	0.95
G	1.60
X	0.55
Y	0.80
Y1	3.20